

## REMARKS

Claims 1 and 3-16 are pending. Favorable consideration is respectfully considered.

At the outset, Applicants thank Examiner Kruer for the helpful suggestions and courteous discussion of the present application held on January 30, 2003. Further, Applicants thank Examiner Kruer for indicating that the following remarks and amendment would further favorable prosecution of the present application.

The rejection of Claims 1-11 under 35 U.S.C. § 103(a) over Maeda et al., Okada et al., Furuta (U.S. '281), Burnell et al., Kubota et al., Furuta et al. (U.S. '004), and/or Inoue et al. is believed to be obviated by the above amendment. Further, none of the above references relied upon by the Office disclose or suggest the claimed invention in light of the following remarks.

As discussed during the Interview with Examiner Kruer, Applicants have amended Claim 1 to include the embodiments of original Claim 2. During the Interview, Examiner Kruer confirmed Applicants' understanding that the only references relied upon by the Office to reject Claim 2 are Maeda et al. and/or Furuta et al. (U.S. '004) in combination with "Applicants' admission" (See page 2 and page 9 of the outstanding Office Action). Therefore, all rejections over any combination of the above-mentioned art that does not apply to Claim 2 are obviated by the above-mentioned amendment to Claim 1 to include the specific embodiments of Claim 2. Accordingly, withdrawal of these grounds of rejection are respectfully requested.

The present invention relates to a resin molded component containing a resin composition having a base resin made up of a thermoplastic resin or a thermosetting resin and an elastic material (see amended Claim 1 above). The elastic material contains at least one copolymer that may be selected from the group ethylene-glycidyl methacrylate-methylacrylate copolymer, ethylene-maleic anhydride-ethylacrylate copolymer, graft

copolymer of ethylene-glycidyl methacrylate copolymer and acrylonitrile-styrene copolymer, and ethylene-glycidyl methacrylate-ethyleneethylacrylate copolymer (see amended Claim 1 above). Further, the claimed invention relates to a printed circuit board containing the claimed resin molding component (See Claim 11 above).

Maeda et al. discloses, at best, a molded product having a printed circuit on a thermoplastic layer (see Abstract). The board disclosed by Maeda et al. may contain a metal layer and a thin wall body containing a cross-linked product. At best, Maeda et al. discloses a mixture of ethylene-ethylacrylate-maleic anhydride terpolymer and an ethylene-methylmethacrylate-2-hydroxyethylmethacrylate terpolymer (see mixture III at column 27, lines 44-54). However, Maeda et al. fail to disclose or suggest that the mixture may contain an elastic material having at least one copolymer selected from the group of ethylene-glycidyl methacrylate-methacrylate copolymer, ethylene-maleic anhydride-ethylacrylate copolymer, graft copolymer of ethylene-glycidylmethacrylate copolymer and acrylonitrile-styrene copolymer and ethylene-glycidylmethacrylate-ethyleneethylacrylate copolymer.

Furuta et al. disclose, at best, a laminate comprising a metallic foil and a layer made of a liquid crystal polyester resin composition (see Abstract). The liquid crystal polyester resin composition may contain rubber (see Abstract). At best, Furuta et al. disclose that the rubber may have a functional group reactive with the liquid crystal polyester disperse phase and may comprise thacrylate-ethylene-unsaturated carboxylic acid glycidyl ester and/or unsaturated glycidyl ether copolymer rubber (see column 9, lines 1-3). Furuta et al. fail to disclose that the rubber is an elastic material that may contain at least one copolymer selected from the group of ethylene-glycidyl-methacrylate-methacrylate copolymer, ethylene-maleic anhydride-ethylacrylate copolymer, graft copolymer of ethylene-glycidyl methacrylate copolymer and acrylonitrile-styrene copolymer, and ethylene-glycidyl methacrylate-ethyleneethylacrylate copolymer.

In direct contrast, the claimed invention relates to a resin molded component that contains, in part, an elastic material having at least one copolymer selected from the group of ethylene-glycidyl methacrylate-methacrylate copolymer, ethylene-maleic anhydride-ethylacrylate copolymer, graft copolymer of ethylene-glycidyl methacrylate copolymer and acrylonitrile-styrene copolymer, and ethylene-glycidyl methacrylate-ethyleneethylacrylate copolymer. Neither Furuta et al. nor Maeda et al. disclose or suggest the above-mentioned copolymers that may be contained in the claimed elastic material. Therefore, these references alone or combined along with the Office's characterization of the "Applicants Admission", which are all relied upon by the Office in support of its obviousness rejection, fail to disclose all aspects of the claimed invention. This is believed to be true even if Applicants accept the Office's characterization of the "Applicants Admission", which applicants do not accept. Accordingly, the Office has failed to provide a *prima facie* case of obviousness and withdrawal of these grounds of rejection is respectfully requested.

The rejection of Claims 1-11 under 35 U.S.C. § 112, second paragraph, is believed to be obviated by the above amendment. More specifically, the claims have been amended to remove the term "rubber-like". Further, as discussed in the above-mentioned interview with Examiner Kruer, Applicants direct the Examiner's attention to page 11, lines 1-2, of the present specification, where Applicants have provided a specific definition for the term "plate-form inorganic filler". More specifically, page 11, lines 1-2, state:

"As a plate-form inorganic fillers, talc, mica, glass flake, monmorillonite, smectite, and the like can be used."

In light of the above, "plate-form inorganic filler" is clearly defined in the present specification. Since the Applicant can be his own lexicographer, and the above-mentioned definition of "plate-form inorganic filler" is not in contrast to any definition of the same known to the Applicants, Applicants respectfully submit that "plate-form inorganic filler" is not indefinite. Please note that Applicants have added Claim 12, which specify the types of plate-form inorganic fillers as disclosed at page 11, lines 1-2, of the present specification. Accordingly, withdrawal of this ground of rejection is respectfully requested.

Applicants respectfully submit that the present application is now in condition for allowance. Favorable reconsideration is respectfully requested. Should anything further be required to place the application in condition for allowance, the Examiner is requested to contact the undersigned by telephone.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.



Norman F. Oblon  
Attorney of Record  
Registration No. 24,618

Thomas W. Barnes  
Registration No. 52,595



22850

Tel.: (703) 413-3000  
Fax: (703) 413-2220  
NFO:TWB\la  
I:\ATTY\TWB\215900US-AM.DOC

**Marked-Up Copy**

Serial No: 09/986,005

Amendment Filed on: HERewith

IN THE CLAIMS

--1. (Amended) A resin molded component, comprising a metal coating treatment [being] provided on the surface thereof by a physical deposition method chosen from [among] at least one method consisting of sputtering, vacuum deposition, and ion plating after the surface is activated by a plasma treatment,

[and characterized in that] wherein the resin molded component [is produced by forming a] comprises a resin composition [combined] comprising a base resin [comprising of] containing a thermoplastic resin or a thermosetting resin [with a rubber-like] and an elastic material wherein the elastic material comprises at least one copolymer selected from the group consisting of ethylene -glycidyl methacrylate-methyl acrylate copolymer, ethylene-maleic anhydride-ethyl acrylate copolymer, graft copolymer of ethylene -glycidyl methacrylate copolymer and acrylonitrile-styrene copolymer, and ethylene -glycidyl methacrylate-ethylene ethyl acrylate copolymer.

3. (Amended) The resin molded component according to [claim] Claim 1, [characterized in that a mixing amount of said rubber-like] wherein the elastic material is present in an amount of from 0.5 to 10 parts in mass to 100 parts in mass of said base resin.

4. (Amended) The resin molded component according to [claim] Claim 1, wherein [characterized in that] said base resin comprises at least one member selected from the group

consisting of polyphthalamide [or] and polyphenylene sulfide [is used as said base resin].

5. (Amended) The resin molded component according to [claim] Claim 1, wherein [characterized in that] said resin composition [is a composition compounded with] further comprises an inorganic filler.

6. (Amended) The resin molded component according to [claim] Claim 5, wherein [characterized in that] said inorganic filler is fibrous [of] having a diameter of from 0.5 to 5  $\mu\text{m}$  [in diameter] and a length of from 10 to 50  $\mu\text{m}$  [in length].

7. (Amended) The resin molded component according to [claim] Claim 5, wherein [characterized in that] said inorganic filler is plate-form.

8. (Amended) The resin molded component according to [claim] Claim 5, wherein [characterized in that] said inorganic filler is a combination of [in] a fiber form [of] having a diameter of from 0.5 to 5  $\mu\text{m}$  [in diameter] and a length of from 10 to 50  $\mu\text{m}$  [in length] [and the] with a plate-form inorganic filler [are used in combination].

9. (Amended) The resin molded component according to [claim] Claim 5, wherein [characterized in that] said inorganic filler is spherical.

10. (Amended) The resin molded component according to [claim] Claim 5, wherein [characterized in that a mixing amount of] said inorganic filler is present in an amount of from 40 to 75% in mass with respect to said whole resin composition.

11. (Amended) [The resin molded component according to claim 1 characterized by being used for] A printed circuit board [boards], comprising the resin molded component according to Claim 1.—

--Claim 2 is cancelled.--

--Claims 12-16 are added.--